



S/N 09/785,006

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Aaron M. Schoenfeld Examiner: Evan P. Pert
Serial No.: 09/785,006 Group Art Unit: 2813
Filed: February 16, 2001 Docket: 303.259US3
Title: GRINDING TECHNIQUE FOR INTEGRATED CIRCUITS

AMENDMENT AND RESPONSE UNDER 37 CFR § 1.111

Commissioner for Patents
Washington, D.C. 20231

Applicant has reviewed the Office Action mailed on September 25, 2001. Please amend the above-identified patent application as follows.

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IN THE CLAIMS

Please substitute the claim set in the appendix entitled Clean Version of Pending Claims for the previously pending claim set. The substitute claim set is intended to reflect amendment of previously pending claims 11, 12, 14 - 18, 20 - 25, 35 - 36, 38 - 41, and 43. The specific amendments to individual claims are detailed in the following marked up set of claims.

11. (Amended) A semiconductor die comprising:
 - a first planar surface having circuitry thereon;
 - a second planar surface opposite the first planar surface;
 - one or more perimeter [edges] side surfaces extending [disposed] between the first planar surface and the second planar surface;
 - a layer of scribe material forming the perimeter side surfaces, the layer of scribe material surrounding the circuitry; and
 - at least a portion of at least one perimeter [edge] side surface of the semiconductor die having a substantially flat, smooth surface[, the portion extending from the first planar surface to the second planar surface].
12. (Amended) The semiconductor die as recited in claim 11, wherein each perimeter [edge] surface has an entirely flat, smooth surface.